

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please cancel claims 1-12 and 39-45.

Listing of Claims:

1-12. (Cancelled)

13. (Original) An integrated circuit active memory device comprising:
a memory device having a data bus containing a plurality of data bus bits;
a logical array of processing elements each of which is coupled to a respective group of the data bus bits, each of the processing elements having an instruction input coupled to receive processing element instructions for controlling the operation of the processing elements, the processing elements in the array being logically arranged in a rectangular grid of logical rows and logical columns in which each processing element lies in only one logical row and one logical column, the processing elements in the array being divided into four sub-arrays each including the processing elements in a respective quartile of the logical array, the processing elements in each of the sub-arrays being physically positioned in a folded arrangement in which the processing elements in different logical rows are physically interleaved with each other and the processing elements in different logical columns are physically interleaved with each other;

a system of conductors coupling the processing elements in each of the logical rows and columns to each other;

an array control unit being operable to generate a sequence of array control unit instructions responsive to each of a plurality of array control unit commands applied to a command input of the array control unit;

a memory device control unit coupled to the memory device, the memory device control unit being operable to generate and to couple respective sets of memory commands to the memory device responsive to each of a plurality of memory device control unit commands applied to a command input of the memory device control unit; and

a command engine coupled to the array control unit and the memory device control unit, the command engine being operable to couple to the array control unit respective sets of the array control unit commands and to couple to the memory device control unit respective sets of the memory device control unit commands responsive to respective task commands applied to a task command input of the command engine.

14. (Original) The active memory device of claim 13 wherein the memory device comprises a dynamic random access memory device.

15. (Original) The active memory device of claim 13 wherein the processing elements in each logical column are separated from each other by one processing element.

16. (Original) The active memory device of claim 13 wherein the processing elements in each logical row are separated from each other by three processing elements.

17. (Original) The active memory device of claim 13 wherein each of the sub-arrays comprises 256 processing elements.

18. (Original) The active memory device of claim 13 wherein the logical array of processing elements comprises a logical upper edge and a logical lower edge, and wherein the processing elements in each of the sub-arrays are physically positioned so that the processing elements adjacent the logical upper edge are physically positioned adjacent the processing elements adjacent the logical lower edge.

19. (Original) The active memory device of claim 13 wherein the logical array is divided into logical upper and lower sections of processing elements separated from each other by a divide line, and wherein the processing elements in each of the sub-arrays are

physically positioned so that the lowest processing elements in the logical upper section are adjacent the highest processing elements in the logical lower section on opposite sides of the divide line.

20. (Original) The active memory device of claim 13 wherein each sub-array is logically divided into logical upper and lower sections of processing elements, and wherein the processing elements in each of the sub-arrays are physically positioned so that the processing elements in the logical upper section are interleaved with the processing elements in the logical lower section.

21. (Original) The active memory device of claim 13, further comprising a plurality of row registers logically positioned along one edge of the logical array at the end of respective logical rows and a plurality of column registers logically positioned along an adjacent edge of the logical array at the end of respective logical columns.

22. (Original) The active memory device of claim 21 wherein the logical array of processing elements comprises a logical upper edge and a logical lower edge, and wherein the column registers are physically positioned so that they are physically adjacent the processing elements that are adjacent the logical upper edge and the logical lower edge of the logical array.

23. (Original) The active memory device of claim 22 wherein the column registers are physically positioned adjacent one physical edge of each sub-array.

24. (Original) The active memory device of claim 21 wherein the logical array of processing elements comprises a logical left edge and a logical right edge, and wherein the row registers are physically positioned so that they are physically adjacent the processing elements that are adjacent the logical left edge and the logical right edge of the logical array.

25. (Original) The active memory device of claim 24 wherein the row registers are physically positioned at the middle of each sub-array.

26. (Original) A computer system, comprising:
a host processor having a processor bus;
at least one input device coupled to the host processor through the processor bus;
at least one output device coupled to the host processor through the processor bus;
at least one data storage device coupled to the host processor through the processor bus; and

an active memory device, comprising:

a memory device having a data bus containing a plurality of data bus bits;
a logical array of processing elements each of which is coupled to a respective group of the data bus bits, each of the processing elements having an instruction input coupled to receive processing element instructions for controlling the operation of the processing elements, the processing elements in the array being logically arranged in a rectangular grid of logical rows and logical columns in which each processing element lies in only one logical row and one logical column, the processing elements in the array being divided into four sub-arrays each including the processing elements in a respective quartile of the logical array, the processing elements in each of the sub-arrays being physically positioned in a folded arrangement in which the processing elements in different logical rows are physically interleaved with each other and the processing elements in different logical columns are physically interleaved with each other;

a system of conductors coupling the processing elements in each of the logical rows and columns to each other;

an array control unit being operable to generate a sequence of array control unit instructions responsive to each of a plurality of array control unit commands applied to a command input of the array control unit;

a memory device control unit coupled to the memory device, the memory device control unit being operable to generate and to couple respective sets of memory commands to the memory device responsive to each of a plurality of memory device control unit commands applied to a command input of the memory device control unit; and

a command engine coupled to the array control unit and the memory device control unit, the command engine being operable to couple to the array control unit respective sets of the array control unit commands and to couple to the memory device control unit respective sets of the memory device control unit commands responsive to respective task commands received from the host processor.

27. (Original) The active memory device of claim 26 wherein the memory device comprises a dynamic random access memory device.

28. (Original) The active memory device of claim 26 wherein the processing elements in each logical column are separated from each other by one processing element.

29. (Original) The active memory device of claim 26 wherein the processing elements in each logical row are separated from each other by three processing elements.

30. (Original) The active memory device of claim 26 wherein each of the sub-arrays comprises 256 processing elements.

31. (Original) The active memory device of claim 26 wherein the logical array of processing elements comprises a logical upper edge and a logical lower edge, and wherein the processing elements in each of the sub-arrays are physically positioned so that the

processing elements adjacent the logical upper edge are physically positioned adjacent the processing elements adjacent the logical lower edge.

32. (Original) The active memory device of claim 26 wherein the logical array is divided into logical upper and lower sections of processing elements separated from each other by a divide line, and wherein the processing elements in each of the sub-arrays are physically positioned so that the lowest processing elements in the logical upper section are adjacent the highest processing elements in the logical lower section on opposite sides of the divide line.

33. (Original) The active memory device of claim 26 wherein each sub-array is logically divided into logical upper and lower sections of processing elements, and wherein the processing elements in each of the sub-arrays are physically positioned so that the processing elements in the logical upper section are interleaved with the processing elements in the logical lower section.

34. (Original) The active memory device of claim 26, further comprising a plurality of row registers logically positioned along one edge of the logical array at the end of respective logical rows and a plurality of column registers logically positioned along an adjacent edge of the logical array at the end of respective logical columns.

35. (Original) The active memory device of claim 34 wherein the logical array of processing elements comprises a logical upper edge and a logical lower edge, and wherein the column registers are physically positioned so that they are physically adjacent the processing elements that are adjacent the logical upper edge and the logical lower edge of the logical array.

36. (Original) The active memory device of claim 35 wherein the column registers are physically positioned adjacent one physical edge of each sub-array.

37. (Original) The active memory device of claim 34 wherein the logical array of processing elements comprises a logical left edge and a logical right edge, and wherein the row registers are physically positioned so that they are physically adjacent the processing elements that are adjacent the logical left edge and the logical right edge of the logical array.

38. (Original) The active memory device of claim 37 wherein the row registers are physically positioned at the middle of each sub-array.

39-45. (Cancelled)